



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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BCW66GLT1G, SBCW66GLT1G

General Purpose Transistor

NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--------------------------------|-----------|-------|------|
| Collector–Emitter Voltage | V_{CEO} | 45 | Vdc |
| Collector–Base Voltage | V_{CBO} | 75 | Vdc |
| Emitter–Base Voltage | V_{EBO} | 5.0 | Vdc |
| Collector Current – Continuous | I_C | 800 | mAdc |
| Collector Current – Pulsed | I_C | 1200 | mAdc |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

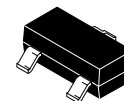
| Characteristic | Symbol | Max | Unit |
|---|-----------------|-------------|----------------------------|
| Total Device Dissipation FR–5 Board (Note 1), $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 225 | mW |
| Thermal Resistance, Junction–to–Ambient | $R_{\theta JA}$ | 556 | $^\circ\text{C}/\text{W}$ |
| Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 300 | mW |
| Thermal Resistance, Junction–to–Ambient | $R_{\theta JA}$ | 2.4 | $\text{mW}/^\circ\text{C}$ |
| Thermal Resistance, Junction–to–Ambient | $R_{\theta JA}$ | 417 | $^\circ\text{C}/\text{W}$ |
| Junction and Storage Temperature | T_J, T_{stg} | –55 to +150 | $^\circ\text{C}$ |

1. FR–5 = $1.0 \times 0.75 \times 0.062$ in.
2. Alumina = $0.4 \times 0.3 \times 0.024$ in 99.5% alumina.

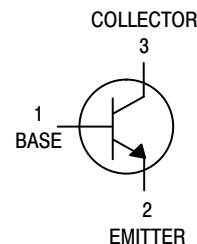


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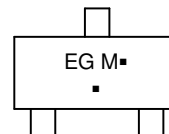
www.onsemi.com



SOT-23
(TO-236)
CASE 318
STYLE 6



MARKING DIAGRAM



EG = Specific Device Code
M = Date Code*
▪ = Pb-Free Package

(*Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping† |
|-------------|---------------------|--------------------|
| BCW66GLT1G | SOT-23 (Pb-Free) | 3,000/Tape & Reel |
| SBCW66GLT1G | SOT-23 (Pb-Free) | 3,000/Tape & Reel |
| BCW66GLT3G | SOT-23 (Pb-Free) | 10,000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BCW66GLT1G, SBCW66GLT1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--|---------------|-----|-----|-----|-------------------------|
| OFF CHARACTERISTICS | | | | | |
| Collector–Emitter Breakdown Voltage ($I_C = 10\text{ mAdc}$, $I_B = 0$) | $V_{(BR)CEO}$ | 45 | – | – | Vdc |
| Collector–Emitter Breakdown Voltage ($I_C = 10\text{ }\mu\text{Adc}$, $V_{EB} = 0$) | $V_{(BR)CES}$ | 75 | – | – | Vdc |
| Emitter–Base Breakdown Voltage ($I_E = 10\text{ }\mu\text{Adc}$, $I_C = 0$) | $V_{(BR)EBO}$ | 5.0 | – | – | Vdc |
| Collector Cutoff Current ($V_{CE} = 45\text{ Vdc}$, $I_E = 0$) ($V_{CE} = 45\text{ Vdc}$, $I_E = 0$, $T_A = 150^\circ\text{C}$) | I_{CES} | – | – | 20 | nAdc μAdc |
| Emitter Cutoff Current ($V_{EB} = 4.0\text{ Vdc}$, $I_C = 0$) | I_{EBO} | – | – | 20 | nAdc |

ON CHARACTERISTICS

| | | | | | |
|--|---------------|------------------------|------------------|--------------------|-----|
| DC Current Gain ($I_C = 100\text{ }\mu\text{Adc}$, $V_{CE} = 10\text{ Vdc}$) ($I_C = 10\text{ mAdc}$, $V_{CE} = 1.0\text{ Vdc}$) ($I_C = 100\text{ mAdc}$, $V_{CE} = 1.0\text{ Vdc}$) ($I_C = 500\text{ mAdc}$, $V_{CE} = 2.0\text{ Vdc}$) | h_{FE} | 50 110 160 60 | – – – – | – – 400 – | – |
| Collector–Emitter Saturation Voltage ($I_C = 500\text{ mAdc}$, $I_B = 50\text{ mAdc}$) ($I_C = 100\text{ mAdc}$, $I_B = 10\text{ mAdc}$) | $V_{CE(sat)}$ | – – | – – | 0.7 0.3 | Vdc |
| Base–Emitter Saturation Voltage ($I_C = 500\text{ mAdc}$, $I_B = 50\text{ mAdc}$) | $V_{BE(sat)}$ | – | – | 2.0 | Vdc |

SMALL–SIGNAL CHARACTERISTICS

| | | | | | |
|--|-----------|-----|---|----|-----|
| Current–Gain — Bandwidth Product ($I_C = 20\text{ mAdc}$, $V_{CE} = 10\text{ Vdc}$, $f = 100\text{ MHz}$) | f_T | 100 | – | – | MHz |
| Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f = 1.0\text{ MHz}$) | C_{obo} | – | – | 12 | pF |
| Input Capacitance ($V_{EB} = 0.5\text{ Vdc}$, $I_C = 0$, $f = 1.0\text{ MHz}$) | C_{ibo} | – | – | 80 | pF |
| Noise Figure ($V_{CE} = 5.0\text{ Vdc}$, $I_C = 0.2\text{ mAdc}$, $R_S = 1.0\text{ k}\Omega$, $f = 1.0\text{ kHz}$, $BW = 200\text{ Hz}$) | NF | – | – | 10 | dB |

SWITCHING CHARACTERISTICS

| | | | | | |
|---|-----------|---|---|-----|----|
| Turn–On Time ($I_{B1} = I_{B2} = 15\text{ mAdc}$) | t_{on} | – | – | 100 | ns |
| Turn–Off Time ($I_C = 150\text{ mAdc}$, $R_L = 150\text{ }\Omega$) | t_{off} | – | – | 400 | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

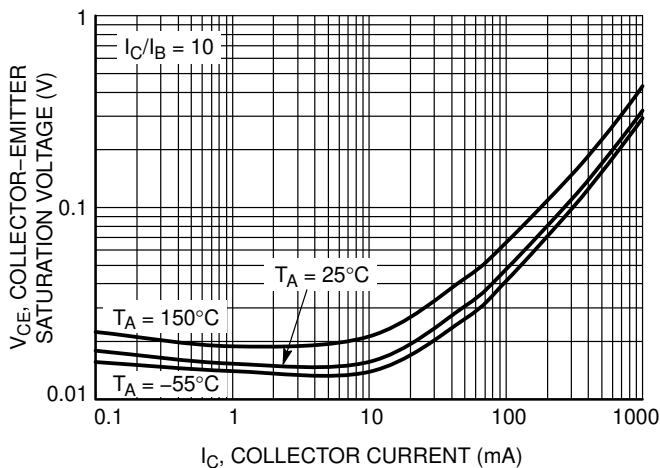


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

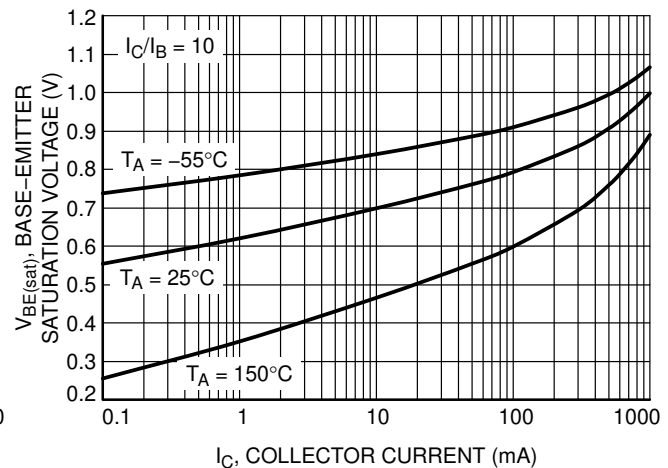


Figure 2. Base Emitter Saturation Voltage vs. Collector Current

BCW66GLT1G, SBCW66GLT1G

TYPICAL CHARACTERISTICS

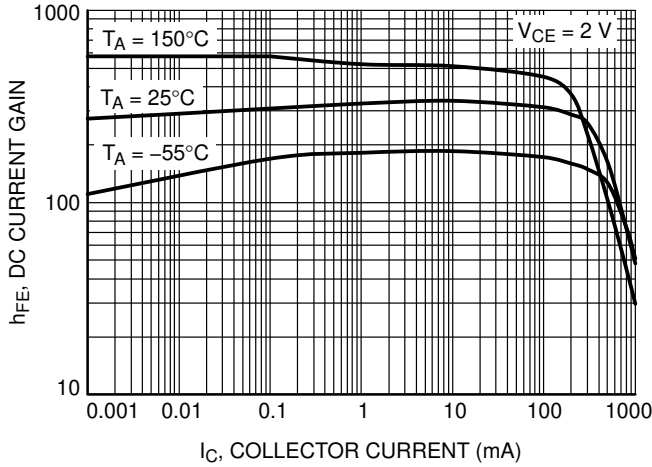


Figure 3. DC Current Gain vs. Collector Current

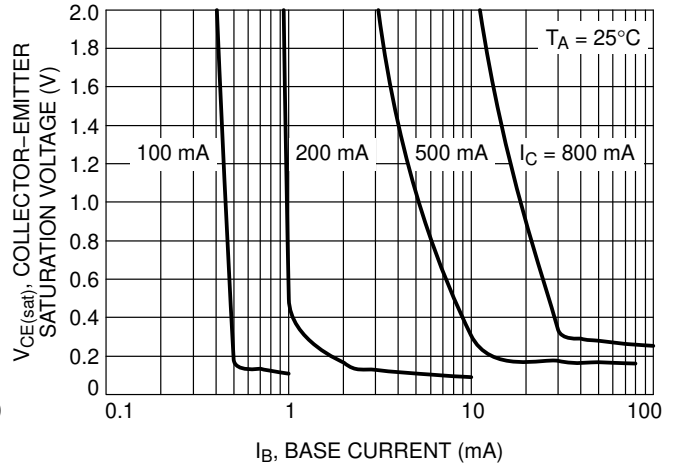


Figure 4. Saturation Region

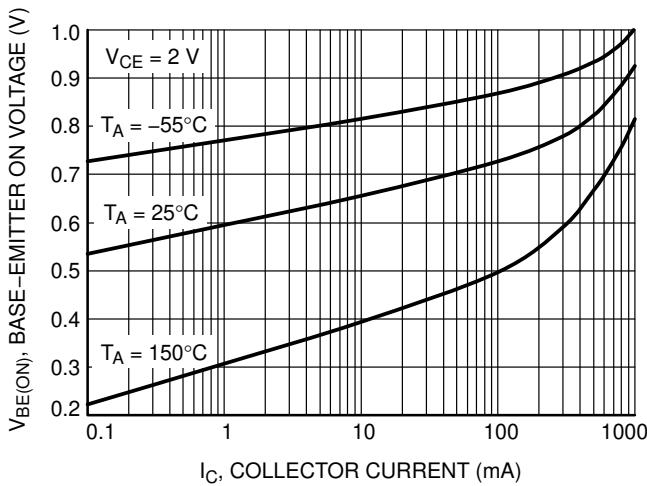


Figure 5. Base-Emitter Turn-On Voltage vs. Collector Current

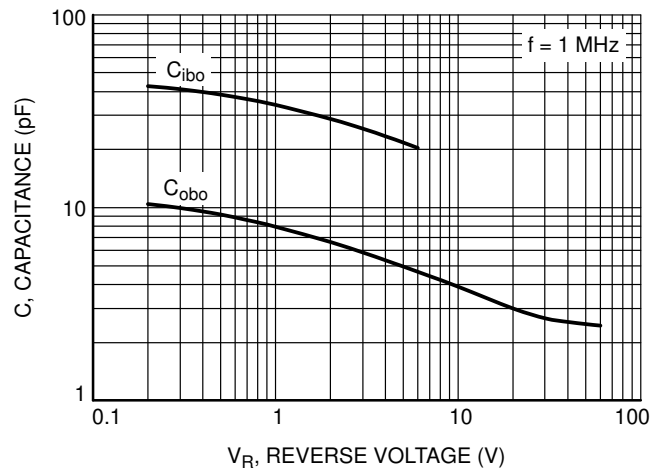


Figure 6. Capacitance

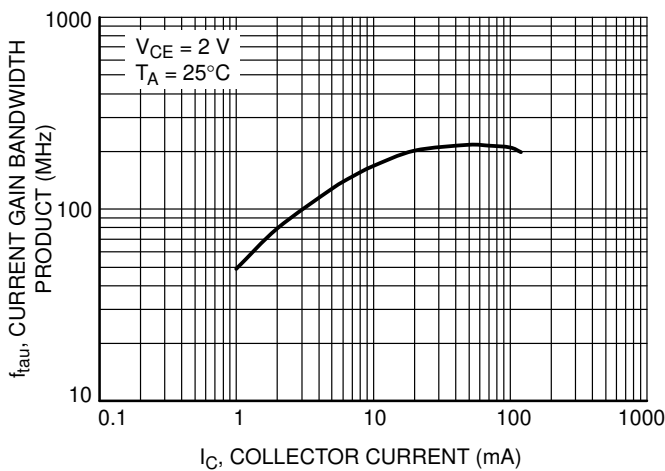


Figure 7. Current Gain Bandwidth Product vs. Collector Current

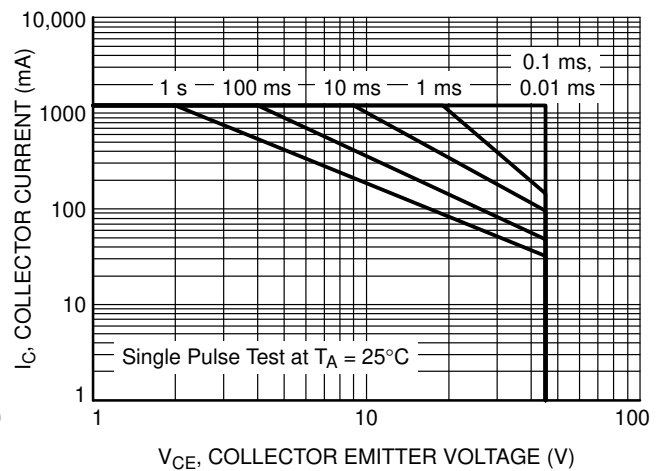
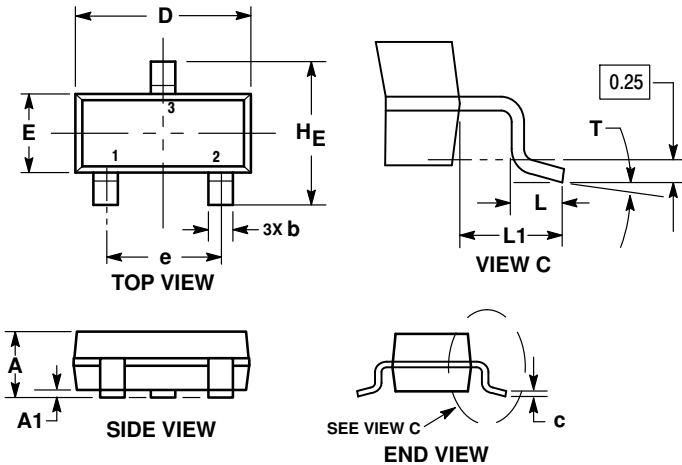


Figure 8. Safe Operating Area

BCW66GLT1G, SBCW66GLT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AR

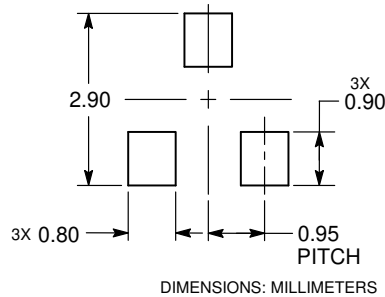


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| c | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| e | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| T | 0° | --- | 10° | 0° | --- | 10° |

- STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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